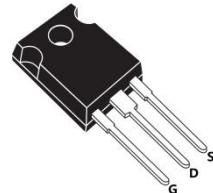


## Features

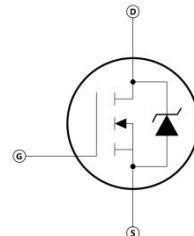
- 100% avalanche tested
- Avalanche ruggedness
- Gate charge minimized
- Very low intrinsic capacitances
- High speed switching
- Very low on-resistance



## General Description

### Applications

- Welder
- UPS
- PV Inverter
- Switching applications



## Electrical ratings

Absolute maximum ratings			
Parameter	Symbol	Value	Unit
Drain-source voltage ( $V_{GS} = 0$ )	$V_{DS}$	1500	V
Gate- source voltage	$V_{GS}$	$\pm 30$	
Drain current (continuous) at $T_c = 25\text{ }^\circ\text{C}$	$I_D$	9	A
Drain current (continuous) at $T_c = 100\text{ }^\circ\text{C}$		6	
Drain current (pulsed)	$I_{DM}$	40	
Total dissipation at $T_c = 25\text{ }^\circ\text{C}$	$P_{TOT}$	350	
Derating factor		2.56	W/ $^\circ\text{C}$
Operating junction temperature	$T_J$	-55 to 150	$^\circ\text{C}$
Storage temperature	$T_{stg}$		

Thermal data			
Parameter	Symbol	Value	Unit
Thermal resistance junction-case max	$R_{thj-case}$	0.39	W/ $^\circ\text{C}$
Thermal resistance junction-ambient max	$R_{thj-amb}$	50	
Maximum lead temperature for soldering purpose	$T_J$	300	

<b>Avalanche characteristics</b>			
<b>Parameter</b>	<b>Symbol</b>	<b>Max value</b>	<b>Unit</b>
Avalanche current, repetitive or not-repetitive (pulse width limited by $T_J$ max)	$I_{AR}$	8	A
Single pulse avalanche energy (starting $T_J = 25^\circ C$ , $I_D = I_{AR}$ , $V_{DD} = 50 V$ )	$E_{AS}$	800	mJ

**Electrical Characteristics ( $T_{vj} = 25^\circ C$  unless otherwise specified)**

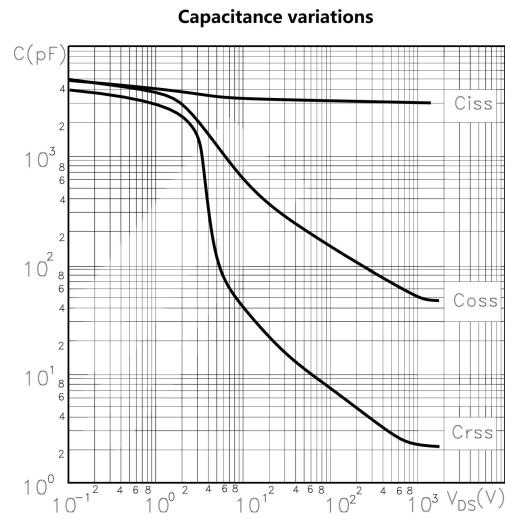
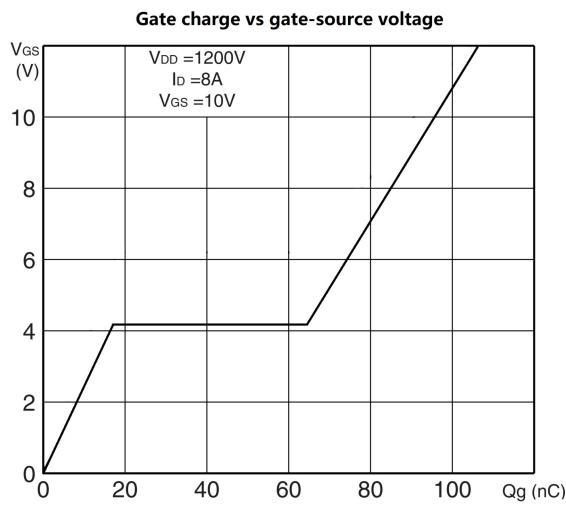
<b>On /off states</b>						
<b>Parameter</b>	<b>Symbol</b>	<b>Test conditions</b>	<b>Min</b>	<b>Typ</b>	<b>Max</b>	<b>Unit</b>
Drain-source breakdown voltage	$V_{(BR)DSS}$	$I_D = 1 \text{ mA}, V_{GS} = 0$	1500			V
Zero gate voltage drain current ( $V_{GS} = 0$ )	$I_{BS}$	$V_{DS} = \text{Max rating}$ $V_{DS}=\text{Max rating}, T_C=125^\circ C$			10 500	$\mu\text{A}$
Gate-body leakage current ( $V_{DS} = 0$ )	$I_{GSS}$	$V_{GS} = \pm 30 V$			$\pm 100$	nA
Gate threshold voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$	3	4	5	V
Static drain-source on resistance	$R_{DS(\text{on})}$	$V_{GS} = 10V, I_D = 4A$	-	2.9	3.5	$\Omega$

<b>Dynamic</b>						
<b>Parameter</b>	<b>Symbol</b>	<b>Test conditions</b>	<b>Min</b>	<b>Typ</b>	<b>Max</b>	<b>Unit</b>
Forward transconductance	$g_f$	$V_{DS} = 15 V, I_D = 4$		7		S
Input capacitance	$C_{iss}$	$V_{DS}=25V,f=1MHz,V_{GS}=0$		3150		pF
Output capacitance	$C_{oss}$			300		
Reverse transfer capacitance	$C_{rss}$			25		
Equivalent Output capacitance	$C_{oss \text{ eq.}}$	$V_{GS}=0, V_{DS}=0 \text{ to } 1200V$		120		
Gate input resistance	$R_g$	f=1MHz Gate DC Bias=0 Test signal level=20mV open drain		2.2		$\Omega$
Total gate charge	$Q_g$	$V_{DD}=1200V, I_D=8A$ $V_{GS}=10V$		85		nC
Gate-source charge	$Q_{gs}$			14		
Gate-drain charge	$Q_{gd}$			48		

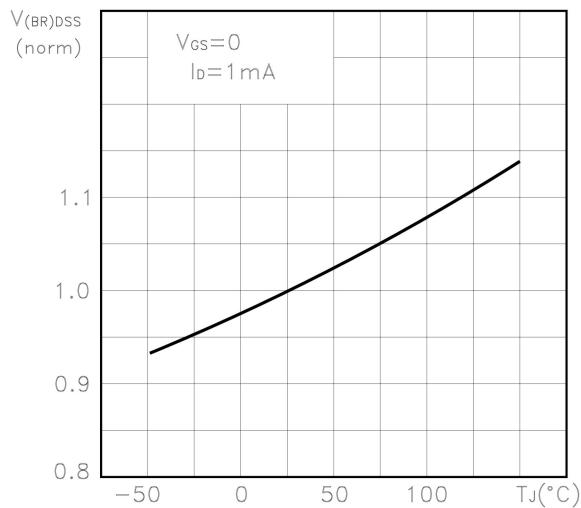
Switching times							
Parameter	Symbol	Test conditions	Min	Typ	Max	Unit	
Turn-on delay time	$t_{d(on)}$	$V_{DD} = 750 \text{ V}$ , $I_D = 4 \text{ A}$ , $R_G = 4.7 \Omega$ , $V_{GS} = 10 \text{ V}$	50			ns	
Rise time	$t_r$		16				
Turn-off-delay time	$t_{d(off)}$		100				
Fall time	$t_f$		80				

Source drain diode							
Parameter	Symbol	Test conditions	Min	Typ	Max	Unit	
Source-drain current	$I_{SD}$	$I_{SD} = 8 \text{ A}$ , $V_{GS} = 0$	8			A	
Source-drain current (pulsed)	$I_{SDM}$		40				
Forward on voltage	$V_{SD}$	$I_{SD} = 8 \text{ A}$ , $V_{GS} = 0$	1.5			V	
Reverse recovery time	$t_{rr}$	$I_{SD} = 8 \text{ A}$ , $dI/dt = 100 \text{ A}/\mu\text{s}$ $V_{DD} = 60 \text{ V}$	950			ns	
Reverse recovery charge	$Q_{rr}$		9			$\mu\text{C}$	
Reverse recovery current	$I_{RRM}$		20			A	
Reverse recovery time	$t_{rr}$		900			ns	
Reverse recovery charge	$Q_{rr}$	$S_D = 8 \text{ A}$ , $dI/dt = 100 \text{ A}/\mu\text{s}$ $V_{DD} = 60 \text{ V}$ $T_J = 150^\circ\text{C}$	8.5			$\mu\text{C}$	
Reverse recovery current	$I_{RRM}$		19			A	

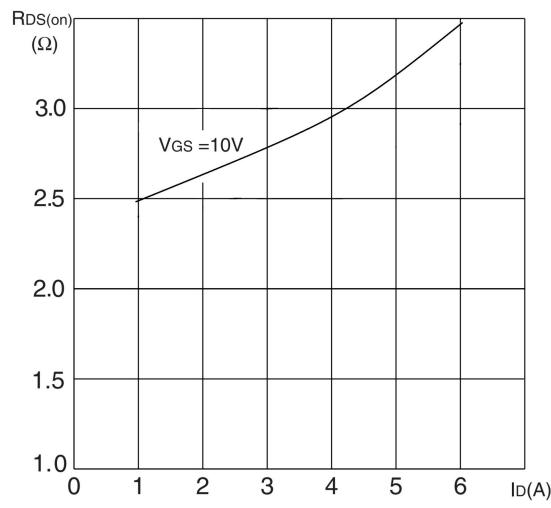
## Electrical characteristics



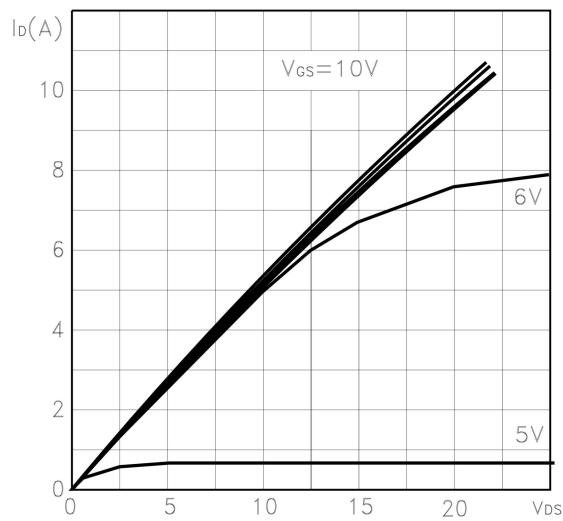
**Normalized BVDSS vs temperature**



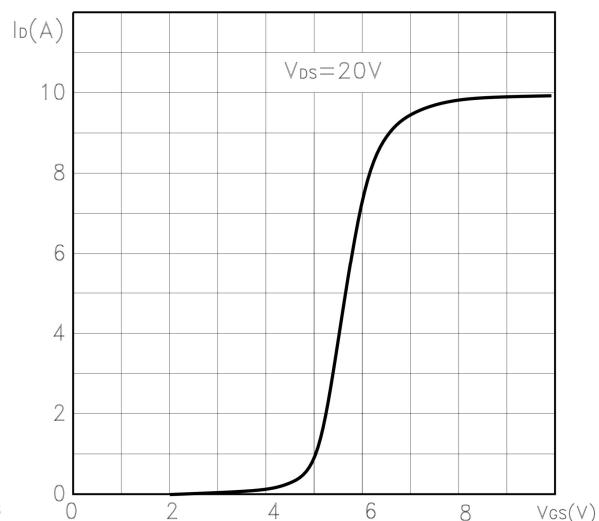
**Static drain-source on resistance**



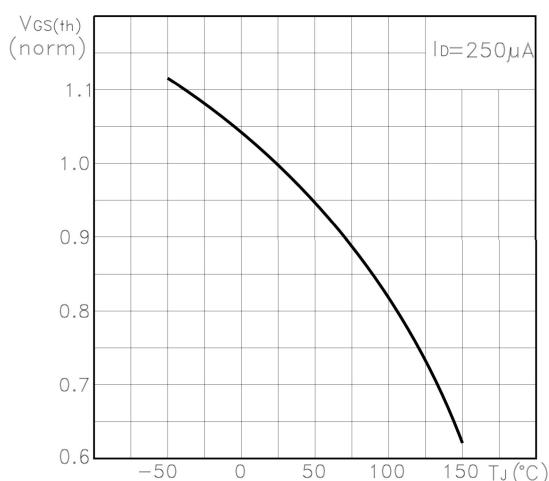
**Output characteristics**



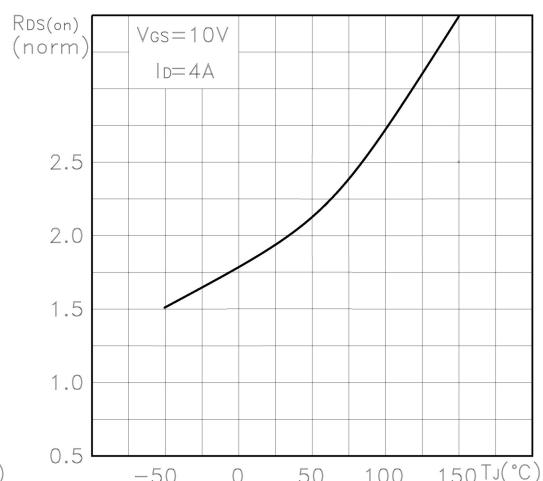
**Transfer characteristics**



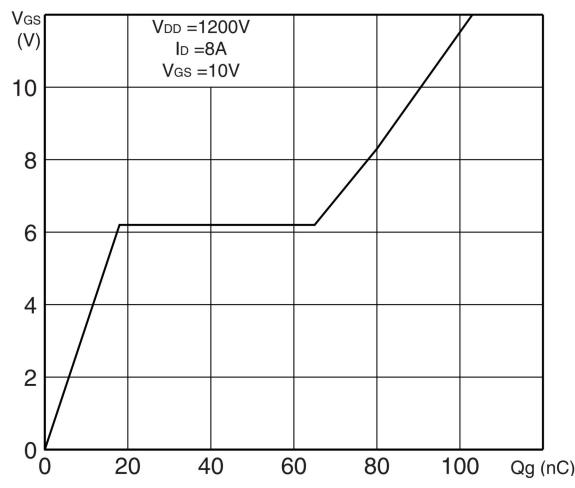
**Normalized gate threshold voltage vs temperature**



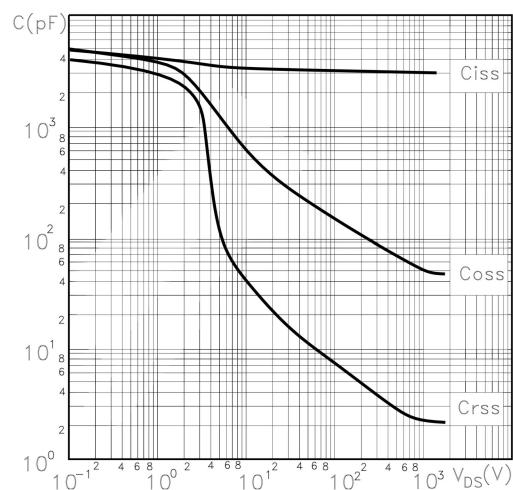
**Normalized on resistance vs temperature**



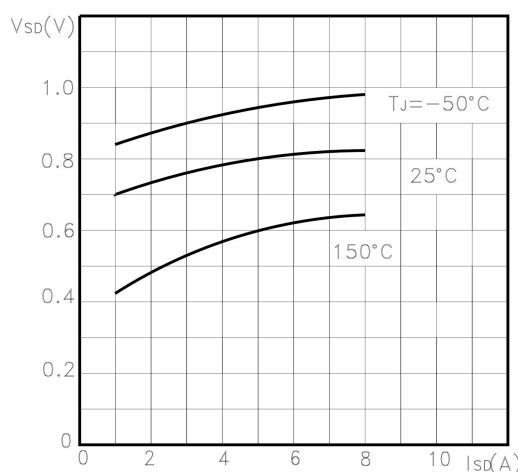
Gate charge vs gate-source voltage



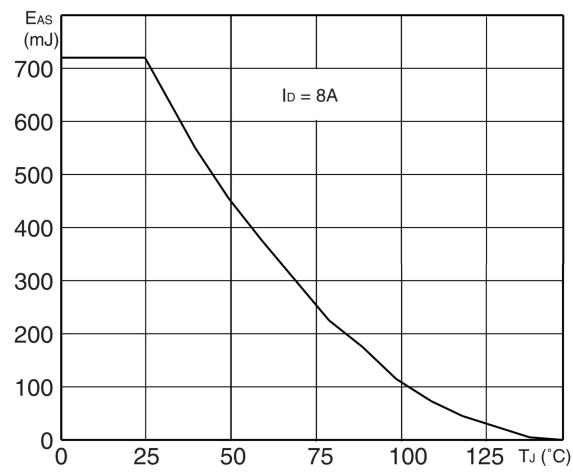
Capacitance variations



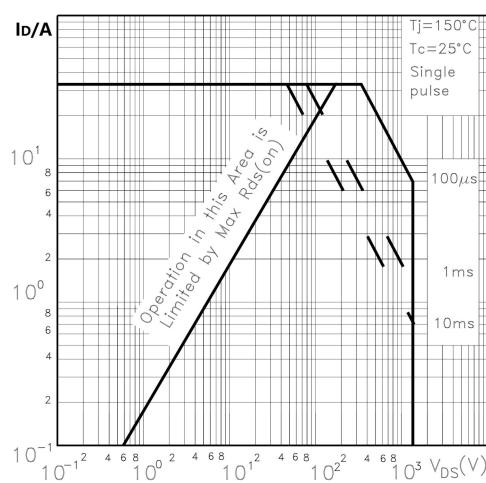
Source-drain diode forward characteristics



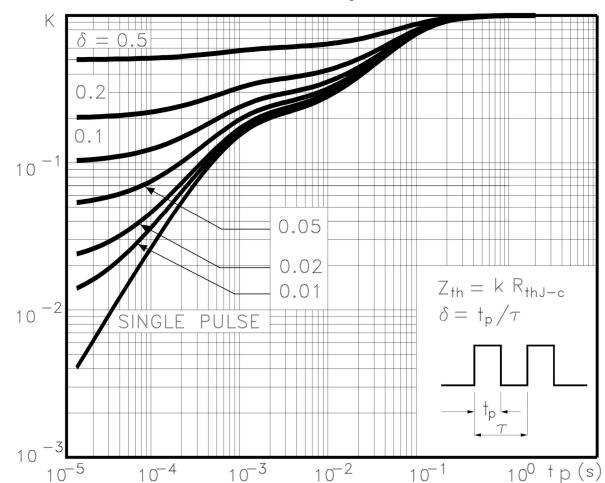
Maximum avalanche energy vs temperature



Safe operating area



Thermal impedance



## Package outline dimension

